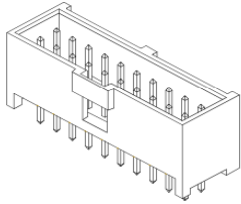


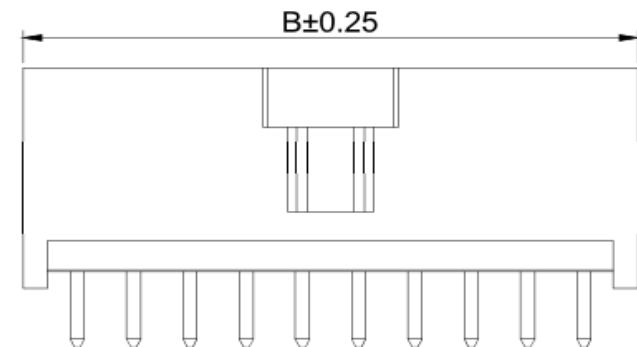
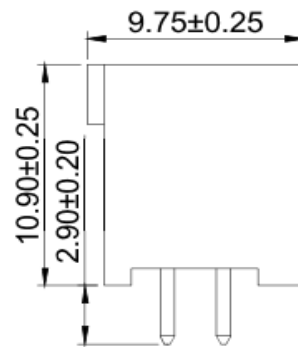
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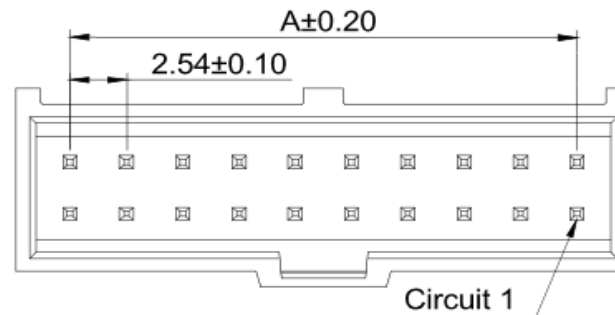
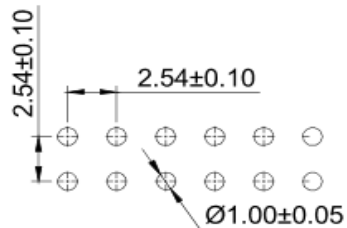
Technical Description

Curent Rating:	3,0A
Voltage Rating:	250V AC,DC
Contact Resistance:	20mΩ max.
Withstanding Voltage:	1500VAC/ DC
Insulation Resistance:	1000MΩ Min
Operating Temperature:	.-40°c to + 105°C
Contact Material:	Brass
Contact Plating:	like Ordering
Insulator Material:	PBT + 30%G.F UL94V-0
Glow-Wire Test	IEC60335-1

Drawing



PCB Layout (mm)



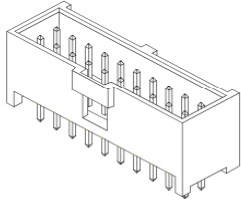
Wire to Board Connector (Wafer)Straight Pin Dual Row	
Part No.:	T68N364
Customer:	

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	23.03.2023
APPD:	Schumi			FINISH	Jamy		Sheet No.	1 from 4	

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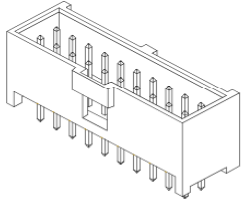
Dimension (mm)

No Pin	A	B	No Pin	A	B
2x2	2,54	8,43	2x30	73,66	79,55
2x3	5,08	10,97	2x31	76,20	82,09
2x4	7,62	13,51	2x32	78,74	84,63
2x5	10,16	16,05	2x33	81,28	87,17
2x6	12,70	18,59	2x34	83,82	89,71
2x7	15,24	21,13			
2x8	17,78	23,67			
2x9	20,32	26,21			
2x10	22,86	28,75			
2x11	25,40	31,29			
2x12	27,94	33,83			
2x13	30,48	36,37			
2x14	33,02	38,91			
2x15	35,56	41,45			
2x16	38,10	43,99			
2x17	40,64	46,53			
2x18	43,18	49,07			
2x19	45,72	51,61			
2x20	48,26	54,15			
2x21	50,80	56,69			
2x22	53,34	59,23			
2x23	55,88	61,77			
2x24	58,42	64,31			
2x25	60,96	66,85			
2x26	63,50	69,39			
2x27	66,04	71,93			
2x28	68,58	74,47			
2x29	71,12	77,01			

Wire to Board Connector (Wafer)Straight Pin Dual Row	
Part No.:	T68N364
Customer:	

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	23.03.2023
APPD:	Schumi			FINISH	Jamy		Sheet No.		2 from 4

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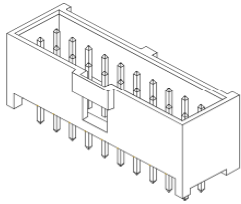
Ordering Informations

Serie	No. Of Position	Contact Plating	Contact Material	Color of Body	Special Function	Special Function	ROHS	Packing		
T68N364	04	GF	BR	BK	N	N	R	BU		

04 = 2x2Pos.	TN = tinned	BR = Brass		N = No Function	N = No Function	R = ROHS Conform	BU = Bulk-Ware
2x2 ~ 2x34Pos.	GF = Gold Flash 0,25~0,5µ		BK = Black			N = NON ROHS Conform	TU = Tube Packing
	GA = Gold 3µ						TC = Tube w. Cap Packing
	GB = Gold 5µ						TR = Tape/Reel Packing w. Cap w. needed
	GC = Gold 10µ						IV = Individual Packing
	GD = Gold 15µ						
	GE = Gold 30µ						
	SA = Selectiv Gold 3µ						
	SB = Selectiv Gold 5µ						
	SC = Selectiv Gold 10µ						
	SD = Selectiv Gold 15µ						
	SE = Selectiv Gold 30µ						

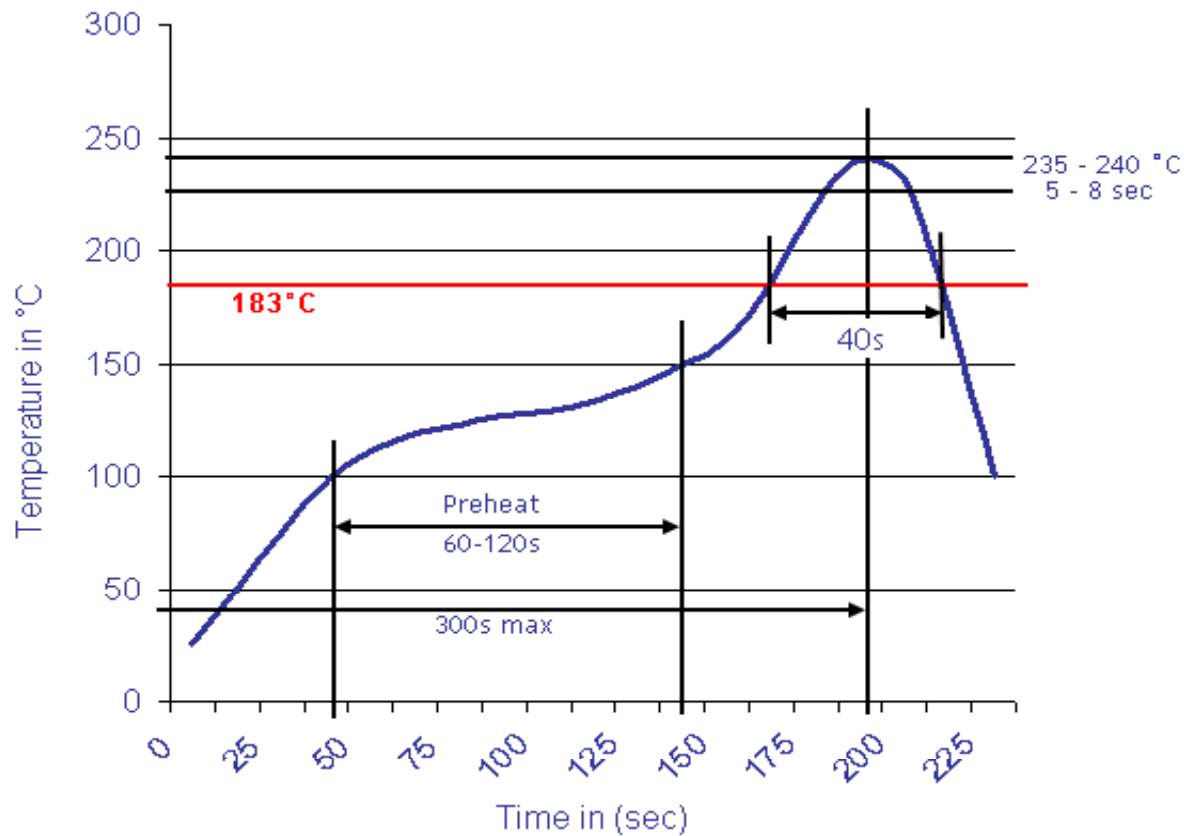
Wire to Board Connector (Wafer)Straight Pin Dual Row	
Part No.:	T68N364
Customer:	

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	23.03.2023
APPD:	Schumi			FINISH	Jamy		Sheet No.		3 from 4



Soldering Profile Curve

Classification Reflow Profile (JEDEC J-STD-020C)



Wire to Board Connector (Wafer)Straight Pin Dual Row	
Part No.:	T68N364
Customer:	

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	23.03.2023
APPD:	Schumi			FINISH	Jamy		Sheet No.	4 from 4	